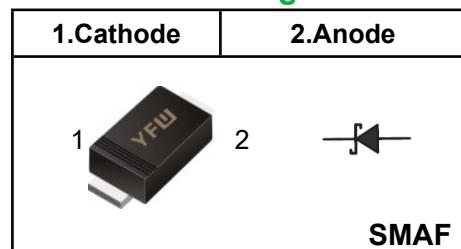


Surface Mount Schottky Barrier Rectifier
Reverse Voltage - 40 to 60 V
Forward Current - 2 A
FEATURES

- ◆ Metal silicon junction, majority carrier conduction
- ◆ For surface mounted applications
- ◆ Low power loss, high efficiency
- ◆ High forward surge current capability
- ◆ For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications
- ◆ Lead free in comply with EU RoHS 2011/65/EU directives


Pinning

Marking Code

SSL24F	SSL24
SSL26F	SSL26

MECHANICAL DATA

- ◆ Case: SMAF
- ◆ Terminals: Solderable per MIL-STD-750, Method 2026
- ◆ Approx. Weight: 27mg / 0.00095oz

Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 ° ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	SSL24F	SSL26F	Units	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	40	60	V	
Maximum RMS voltage	V_{RMS}	28	42	V	
Maximum DC Blocking Voltage	V_{DC}	40	60	V	
Maximum Average Forward Rectified Current	$I_{(AV)}$	2.0			A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed On Rated Load (JEDEC method)	I_{FSM}	50	40	A	
Maximum Instantaneous Forward Voltage at 2 A	V_F	0.45	0.52	V	
Maximum Instantaneous Reverse Current $T_A = 25^\circ C$ at Rated DC Reverse Voltage $T_A = 100^\circ C$	I_R	0.5 10	0.3 5	mA	
Typical Junction Capacitance ⁽¹⁾	C_J	290	130	pF	
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$	65			$^\circ C/W$
Operating Junction Temperature Range	T_J	-55 ~ +150			$^\circ C$
Storage Temperature Range	T_{stg}	-55 ~ +150			$^\circ C$

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Forward Current Derating Curve

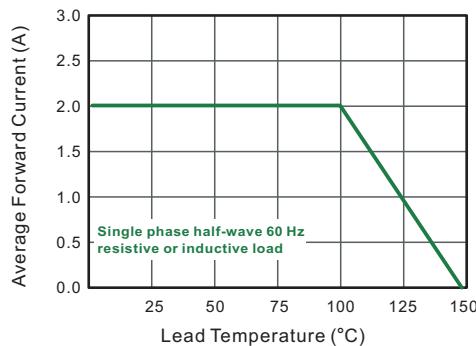


Fig.2 Typical Reverse Characteristics

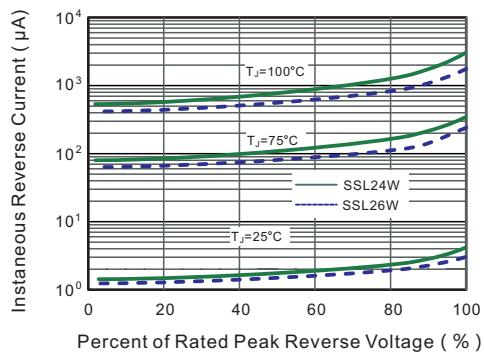


Fig.3 Typical Forward Characteristic

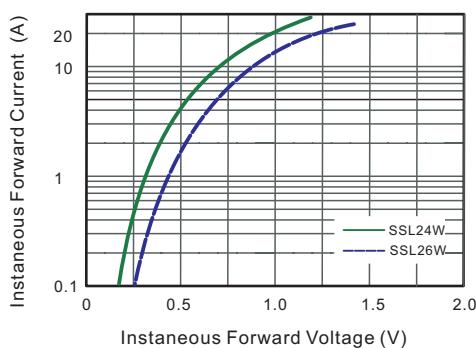


Fig.4 Typical Junction Capacitance

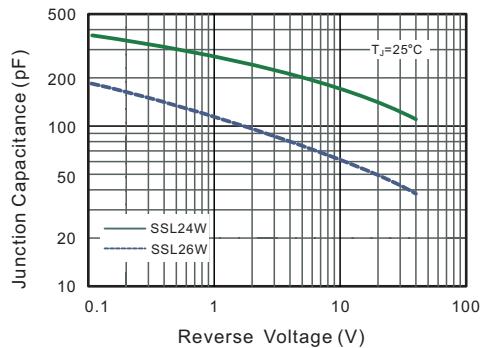


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

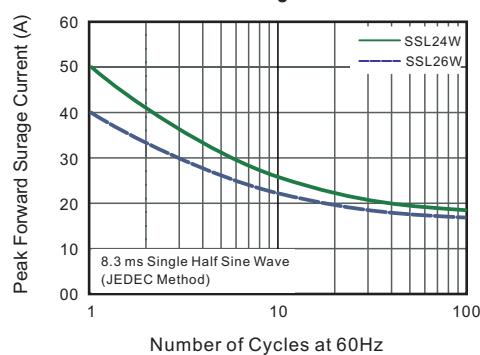
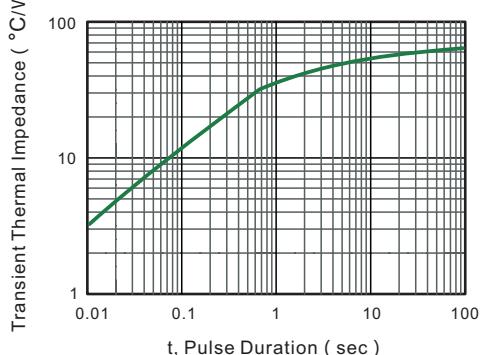


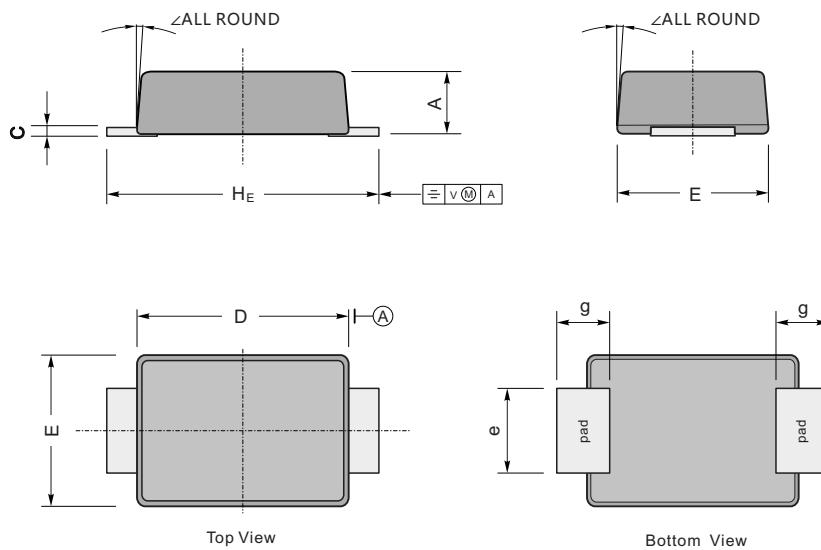
Fig.6- Typical Transient Thermal Impedance



Package Outline

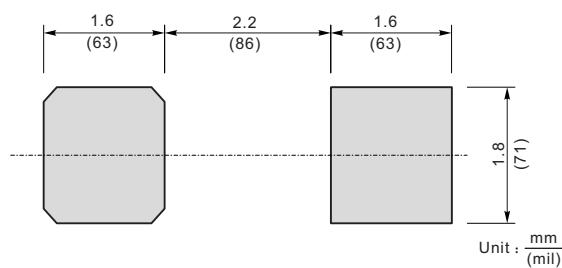
SMAF

Plastic surface mounted package; 2leads



UNIT		A	C	D	E	e	g	H _E	∠
mm	max	1.1	0.20	3.7	2.7	1.6	1.2	4.9	7°
	min	0.9	0.12	3.3	2.4	1.3	0.8	4.4	
mil	max	43	7.9	146	106	63	47	193	7°
	min	35	4.7	130	94	51	31	173	

The recommended mounting pad size



Summary of Packing Options

Package	Packing Description	Packing Quantity	Industry Standard
SMAF	Tape/Reel, 13" reel	10000	EIA-481-1
	Tape/Reel, 7" reel	3000	EIA-481-1